

# William Grossman

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**Education:** **Stanford University** - MS Mechanical Engineering 11' (Focus in Mechatronics)  
**University of California, Berkeley** - BS Mechanical Engineering 09'

**Experience:** **Mechatronic Design**

- ME 218ABC (SPDL) - Embedded system and electromechanical design
- Lots of embedded C experience in several IDEs (Codewarrior, MPLab, TI Workbench)
- Platforms: TI, PIC, Motorola, Arduino

**Apple iPod Accessories Firmware Intern**

*Apple Inc, Cupertino Ca*

*Summer 2010*

- Managed a large embedded C project started by previous intern
- Integrated new features into project and fixed bugs with previous features
- Interfaced with an EE intern in order to develop the hardware alongside the software
- Designed and implemented a communication protocol to interface the project to a computer
- Software will be used to test all Apple headphones on assembly line

**Graduate Student Instructor**

*UC Berkeley and Stanford*

*Fall 2008 - Spring 2011*

- Cumulative of 3 years worth of teaching Physics, EE, and ME courses
- Managed an EE lab with 16 computer stations/scopes/power supplies (ME 218 TA)
- Debugged issues with equipment and assisted students with HW/SW design and implementation
- Developed mechanical and software infrastructure for final project (please see [website](#))
- Held discussion sections and lab sections and helped students with all facets of the class
- Served as interface between students and professor
- Took care of course administrative duties (while head TA at UC Berkeley)
- Oversaw other GSIs and held weekly meetings (while head TA at UC Berkeley)

**Aeromechanical R/D Intern**

*Aerovironment, Simi Valley Ca*

*Summer of 2007 and 2008*

- Prototyped a new kind of micro-package delivery system for small UAVs
- Took project from initial concepts through final designs and testing
- Proved accurate delivery of payloads up to 100 grams
- Project received future funding
- Invited back next summer to work on UAV project developing a new airframe for military
- Designed enclosure and developed waterproofing technics for rugged battery interface for UAV

**Chief Pilot/Hardware Technician**

*C3UV, Berkeley Ca*

*Spring 2006, 2008, and Summer 2009*

- Piloted for demo's and software validation for UC Berkeley UAV research team
- Integrated 5 new UAV's ([Bat IV's](#)) into existing fleet
- Designed, prototyped, and integrated new hardware systems on UAVs

**Awards:** **Jarret Award**

- Won most outstanding [project in machine design](#)

**Skills:**

**Software** - EAGLE, Matlab, Solidworks, LabView, G-Code

**Shop and Material Experience** - CNC, Mill, Lathe, Mold Making, Composites, Some Welding

**Interests** - Mechatronics, Private Pilot, Paraglider, Motorcycles, Extensive RC experience

Please visit my [website](#) for an up to date account of all of my past projects